



12500 TI Boulevard, MS 8640, Dallas, Texas 75243

PCN# 20130708002
Qualification of TI Clark as an Additional Assembly, Bump, and Test site
for Select Devices on WCSP and QFN Package
Change Notification / Sample Request

Date: 7/11/2013
To: MOUSER PCN

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

We request you acknowledge receipt of this notification within **30** days of the date of this notice. Lack of acknowledgement of this notice within 30 days constitutes acceptance of the change. If you require samples or additional data to support your evaluation, please request within 30 days.

The changes discussed within this PCN will not take effect any earlier than **90** days from the date of this notification, unless customer agreement has been reached on an earlier implementation of the change. This notification period is per TI's standard process.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice, contact your local Field Sales Representative or the PCN Manager (PCN_ww_admin_team@list.ti.com).

Sincerely,

PCN Team
SC Business Services
Phone: +1(214) 480-6037
Fax: +1(214) 480-6659

20130708002
Attachment: 1

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
TPS22913BYZVR	null
TPS22913BYZVT	null

Technical details of this Product Change follow on the next page(s).

PCN Number:	20130708002	PCN Date:	07/11/2013
Title:	Qualification of TI Clark as an Additional Assembly, Bump, and Test site for Select Devices on WCSP and QFN Package		
Customer Contact:	PCN Manager	Phone:	+1(214)480-6037
Dept:	Quality Services		
Proposed 1st Ship Date:	10/11/2013	Estimated Sample Availability:	Date Provided at Sample request
Change Type:			
<input checked="" type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Assembly Process
<input type="checkbox"/>	Design	<input type="checkbox"/>	Assembly Materials
<input checked="" type="checkbox"/>	Test Site	<input type="checkbox"/>	Electrical Specification
<input checked="" type="checkbox"/>	Wafer Bump Site	<input type="checkbox"/>	Mechanical Specification
<input type="checkbox"/>	Wafer Fab Site	<input type="checkbox"/>	Packing/Shipping/Labeling
<input type="checkbox"/>		<input type="checkbox"/>	Test Process
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Bump Material
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Bump Process
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Materials
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Process
PCN Details			
Description of Change:			
Qualification of JCAP as an Additional Assembly, Bump, and Test site for Select Devices on WCSP Package. Assembly differences are shown in the following table:			
Group 1: WCSP current assembly – JCAP-AT			
	JCAP-AT	Clark-AT	
Bump Site	JCAP-FAB	Clark-BP	
Solder Ball	MA22008110	4207848	
Group 2: QFN current assembly – TIM. No Assembly material differences			
	TIM	TI Clark	
Mold compound	4208625	4208625	
Wire	0.96mil Au	0.96 mil Au	
Test coverage, insertions, conditions will remain consistent with current testing and verified with test MQ.			
Reason for Change:			
Continuity of supply.			
Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):			
None			

Changes to product identification resulting from this PCN:

Assembly Site		
JCAP-AT	Assembly Site Origin (22L)	ASO: JCP
TIM	Assembly Site Origin (22L)	ASO: MLA
Clark-AT	Assembly Site Origin (22L)	ASO: QAB

Sample product shipping label to show code location only - not actual product label

TEXAS INSTRUMENTS
 MADE IN: Philippines
 2DC: 878381
 MSL 3 /260C/168 HR SEAL DT 10/11/11
 OPT: ITEM: 030DB107CMR-0& 19
 LBL: 1A (L)T0:1168
 (1P) PTWL6030DB107CMR
 (Q) 1908 (D) 1136
 (31T) LOT: 1606673PHI
 (4W) SWR(1T) 8550440Z48
 (P)
 (2P) REV: A (V) 0033317
 (20L) CS0: RFB (21L) CC0: USA
 (22L) ASO: PHI (23L) AC0: PHL

Assembly Site Code: Clark-AT=I, JCAP-AT=P

Product Affected:

Group 1 Device: WCSP package

TPS22913BYZVR	TPS22913BYZVT
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Group 2 : QFN package

BQ27410DRZR-G1	BQ27510DRZR-G3
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Qualification Data – Group 1 Device

This qualification has been specifically developed for the validation of this change. The qualification data validates that the proposed change meets the applicable released technical specifications.

Qual Vehicle : TPS22913BYZV (MSL1-260C)

Package Construction Details

Assembly & Bump Site:	CLARK	Bump Composition:	SnAgCu
# Pins-Designator, Family:	4-YZV, WCSP/DSBGA	Bump Diameter:	0.25mm
Qualification:	<input type="checkbox"/> Plan <input checked="" type="checkbox"/> Test Results		
Reliability Test	Conditions	Sample Size/Fail	
Electrical Characterization	-	30/0	
Manufacturability (Assembly)	(per mfg site specifications)	Pass	

Reference Qualification

Qual Vehicle : TXS0104EYZTR (MSL1-260C)				
Package Construction Details				
Assembly & Bump Site:	CLARK	Bump Composition:	SnAgCu	
# Pins-Designator, Family:	12-YZT, WCSP/DSBGA	Bump Diameter:	0.25mm	
Qualification: <input type="checkbox"/> Plan <input checked="" type="checkbox"/> Test Results				
Reliability Test	Conditions	Sample Size/Fail		
		Lot 1	Lot 2	Lot 3
**Steady-state Life Test	150C (300 Hrs)	77/0	77/0	77/0
**High Temp. Storage Bake	150C (1000hrs)	77/0	77/0	77/0
**Biased HAST	130C/85%RH (96 Hrs)	77/0	77/0	77/0
**Unbiased HAST	130C/85%RH (96 Hrs)	77/0	77/0	77/0
**Temperature Cycle	-55C/+125C (1000 Cyc)	77/0	77/0	77/0
Manufacturability (Assembly)	(per mfg site specifications)	Pass	Pass	Pass
** Note: Moisture Preconditioning (MSL1-260C)				

Qualification Data – Group 2 Device

This qualification has been specifically developed for the validation of this change. The qualification data validates that the proposed change meets the applicable released technical specifications.				
Qual Vehicle : SN8034DRZ (MSL2-260C)				
Package Construction Details				
Assembly Site:	CLARK	Mold Compound:	4208625	
# Pins-Designator, Family:	12-DRZ, QFN	Mount Compound:	4207768	
Lead Finish, Base :	NiPdAu, Cu	Bond Wire:	0.96mil Au	
Qualification: <input type="checkbox"/> Plan <input checked="" type="checkbox"/> Test Results				
Reliability Test	Conditions	Sample Size/Fail		
		Lot 1	Lot 2	Lot 3
**Autoclave	121C (96 Hrs)	77/0	77/0	77/0
**High Temp. Storage Bake	170C (420hrs)	77/0	77/0	77/0
**Temperature Cycle	-65C/+150C (500 Cyc)	82/0	82/0	82/0
X-Ray	(top side only)	5/0	5/0	5/0
Manufacturability (Assembly)	(per mfg site specifications)	Pass	Pass	Pass
Moisture Sensitivity	MSL2-260C	12/0	12/0	12/0
** Moisture Preconditioning (MSL2-260C)				

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com